

# 2.5V Drive Pch MOSFET

## RTL020P02FRA

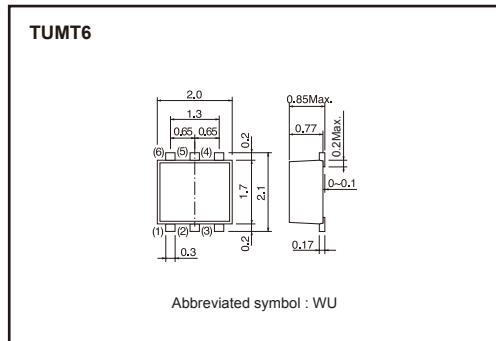
### ●Structure

Silicon P-channel  
MOSFET

### ●Features

- 1) Low on-resistance. (180mΩ at 2.5V)
- 2) High power package.
- 3) High speed switching.
- 4) Low voltage drive. (2.5V)

### ●Dimensions (Unit : mm)



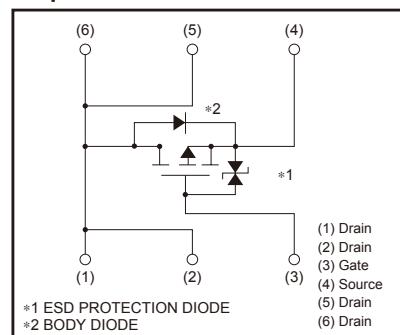
### ●Applications

DC-DC converter

### ●Packaging specifications

Type	Package	Taping
	Code	TR
	Quantity (pcs)	3000
RTL020P02FRA		○

### ●Equivalent circuit



### ●Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Drain-source voltage	V <sub>DSS</sub>	-20	V
Gate-source voltage	V <sub>GSS</sub>	±12	V
Drain current	Continuous I <sub>D</sub>	±2	A
	Pulsed I <sub>DP</sub>	±8	A
Source current (Body diode)	Continuous I <sub>S</sub>	-0.8	A
	Pulsed I <sub>SP</sub>	-8	A
Total power dissipation	P <sub>D</sub>	1	W
Channel temperature	T <sub>ch</sub>	150	°C
Range of Storage temperature	T <sub>stg</sub>	-55 to +150	°C

\*1 Pw≤10μs, Duty cycle≤1%

\*2 Mounted on a ceramic board

### ●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	R <sub>th(ch-a)</sub> *	125	°C / W

\* Mounted on a ceramic board.

## Transistors

## ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	—	—	±10	μA	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	-20	—	—	V	I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	—	—	-1	μA	V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	-0.7	—	-2.0	V	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1mA
Static drain-source on-state resistance	R <sub>DSS (on)</sub> *	—	100	135	mΩ	I <sub>D</sub> = -2A, V <sub>GS</sub> = -4.5V
		—	110	150	mΩ	I <sub>D</sub> = -2A, V <sub>GS</sub> = -4V
		—	180	250	mΩ	I <sub>D</sub> = -1A, V <sub>GS</sub> = -2.5V
Forward transfer admittance	Y <sub>fs</sub>   *	1.2	—	—	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1A
Input capacitance	C <sub>iss</sub>	—	430	—	pF	V <sub>DS</sub> = -10V
Output capacitance	C <sub>oss</sub>	—	80	—	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	—	55	—	pF	f=1MHz
Turn-on delay time	t <sub>d (on)</sub> *	—	11	—	ns	I <sub>D</sub> = -1A V <sub>DD</sub> = -15V V <sub>GS</sub> = -4.5V
Rise time	t <sub>r</sub> *	—	13	—	ns	R <sub>L</sub> =15Ω
Turn-off delay time	t <sub>d (off)</sub> *	—	38	—	ns	R <sub>G</sub> =10Ω
Fall time	t <sub>f</sub> *	—	12	—	ns	
Total gate charge	Q <sub>g</sub> *	—	4.9	—	nC	V <sub>DD</sub> = -15V R <sub>L</sub> =7.5Ω
Gate-source charge	Q <sub>gs</sub> *	—	1.2	—	nC	V <sub>GS</sub> = -4.5V R <sub>G</sub> =10Ω
Gate-drain charge	Q <sub>gd</sub> *	—	1.3	—	nC	I <sub>D</sub> = -2A

\*Pulsed

## ●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub>	—	—	-1.2	V	I <sub>S</sub> = -0.8A, V <sub>GS</sub> =0V

## Transistors

## ●Electrical characteristic curves

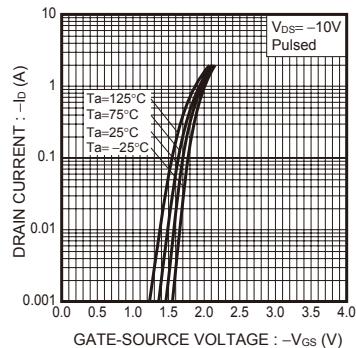


Fig.1 Typical Transfer Characteristics

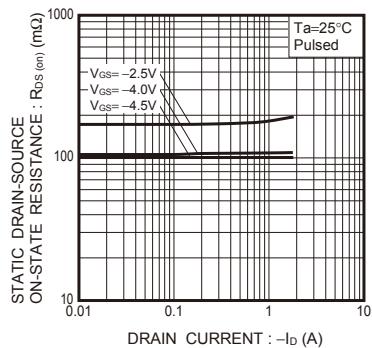


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

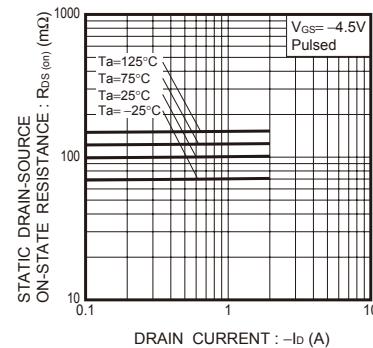


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

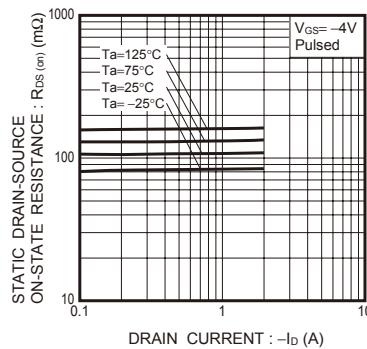


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

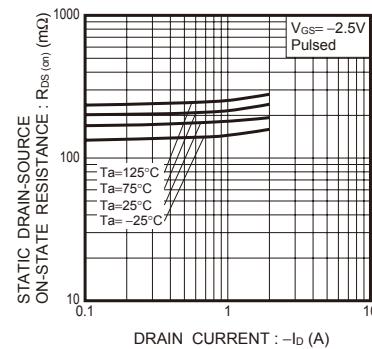


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

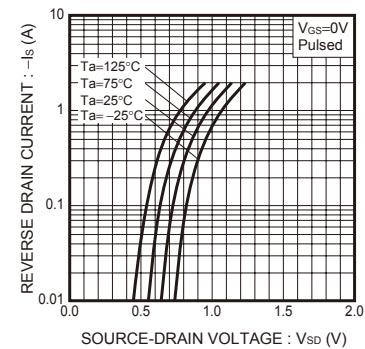


Fig.6 Reverse Drain Current vs. Source-Drain Voltage

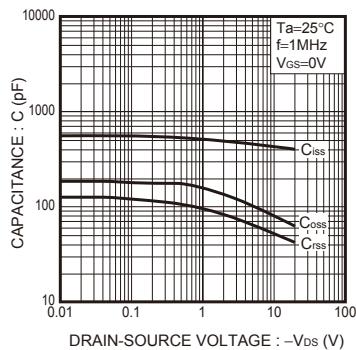


Fig.7 Typical Capacitance vs. Drain-Source Voltage

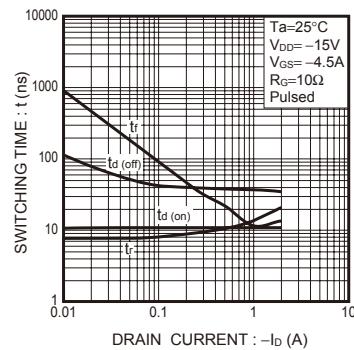


Fig.8 Switching Characteristics

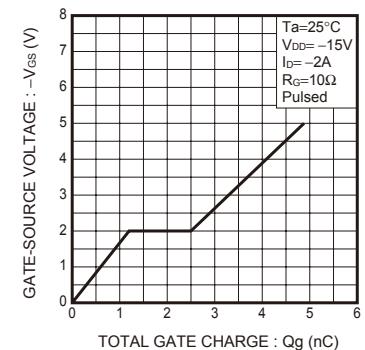


Fig.9 Dynamic Input Characteristics

## Transistors

## ● Measurement circuits

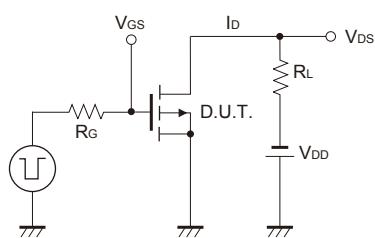


Fig.10 Switching Time Measurement Circuit

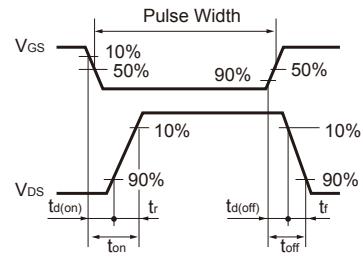


Fig.11 Switching Waveforms

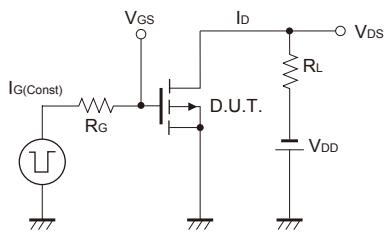


Fig.12 Gate Charge Measurement Circuit

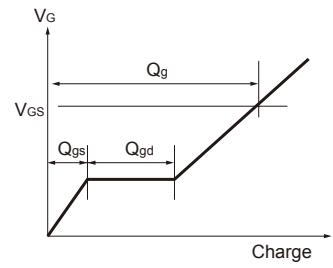


Fig.13 Gate Charge Waveforms